

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. - 34. (cancelled).

35. (previously presented) An electroplating device for wafer metallization of a wafer for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold the wafer above said reservoir,

a counter-electrode in said reservoir,

means adapted for passing current between said counter-electrode and the wafer in said holder,

a pump adapted for pumping electrolyte from said reservoir against the wafer in said holder,

a non-conducting porous separator between said wafer holder and said counter-electrode.

36. (previously presented) An electroplating device for wafer metallization of a wafer for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold the wafer above said reservoir,

a counter-electrode in said reservoir, said counter-electrode disposed concentrically with said holder,

means adapted for passing current between said counter-electrode and the wafer in said holder,

a pump adapted for pumping electrolyte from said reservoir against the water in said holder, and

Wherein the diameter of said counter-electrode is smaller than the diameter of said wafer holder.

37. (cancelled)

38. (previously presented) An electroplating device of wafers for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold a wafer above said reservoir,

a counter-electrode in said reservoir,

means for passing current between said counter-electrode and a wafer in said holder,

a pump for pumping electrolyte from said reservoir against said wafer, and

a distributor positioned in said reservoir including a disk having a plurality of holes adapted to provide a flow of electrolyte through the disk that is uniform along a radius of the disk.